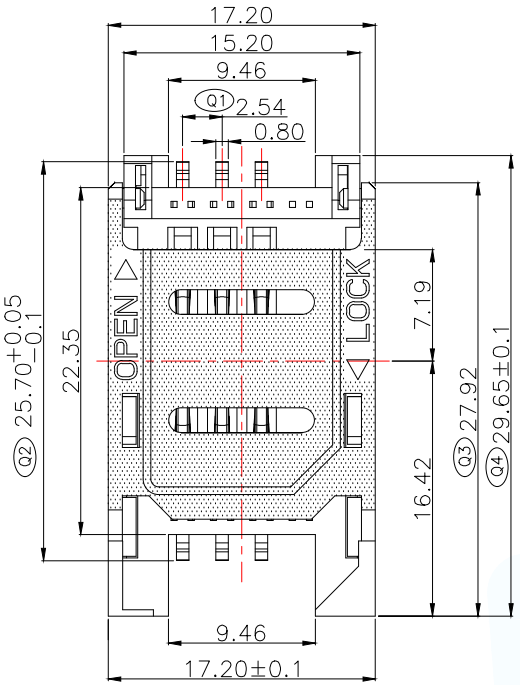
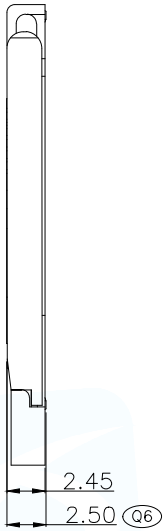
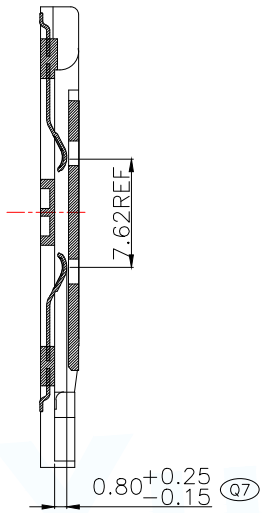
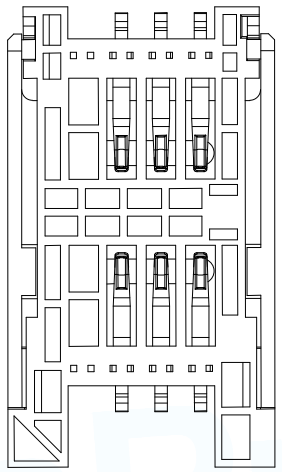
ROHS Compliant

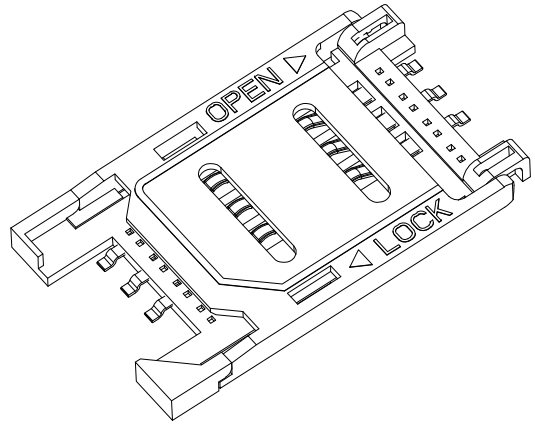
MAPX	MODIFICATION	DATE	DRAW	APPROVE

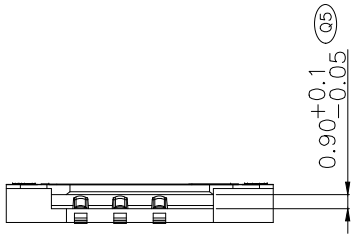








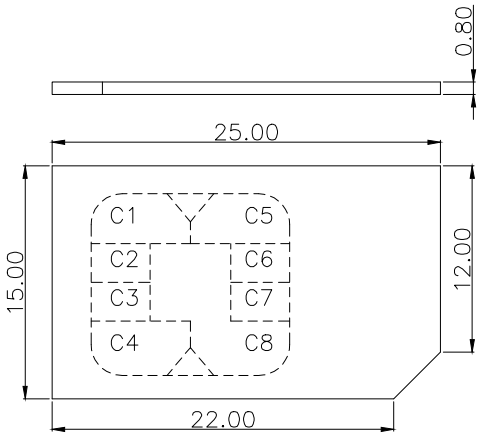


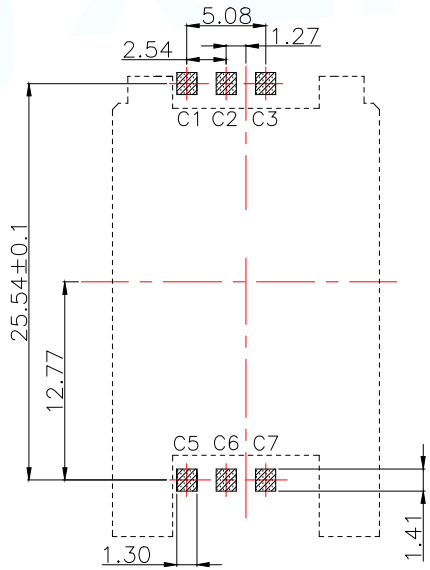


MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

Q8 SPECIFICATION:

1.寿命:10000CYCLES MIN.
2.CONTACT FORCE:0.2~1.0N.(卡片厚度0.76MM)
3.接触阻抗:50mΩ, TYPICAL,100mΩ MAX.
4.绝缘阻抗:MIN 1000MΩ/500V DC .
5.OPEN/LOCK FORCE: 6N ± 3N
6.平贴:IR前后CP8 0.10MM MAX;塑胶0.20MM MAX.
7.QX为重点检验尺寸.
8.工作范围:−40℃~+ 85℃





PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

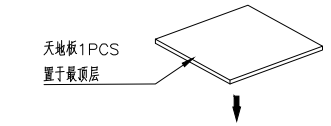
Table A

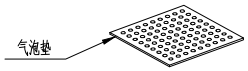
材质	塑胶	LCP E130i HF WHITE
	端子	C5210R−H T=0.20mm HF
端子电镀	整体打镍底50U"MIN,接触区刷金3U"MIN, 焊接区浸镀纯雾锡100U"MIN.	

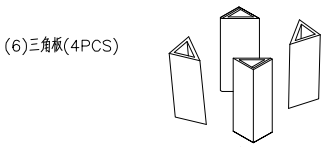
MANUFACTURE DWG	东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co,Ltd			
UNLESS OTHERWISE SPECIFED TOLERANCES		TITLE:MINI SIM CARD HINGED 全塑 6P无柱 白色		
		PAR	SIM−107−ARP6W	
		DWN		
		CHKD		
		APVD		
DECIMALS:	ANGLES:	SCALE1:1	UNIT:MM	
X.X:±0.15	X.°:±3°			
X.XX:±0.10	X.X':±2°			
X.XXX:±0.08	X.XX":±1°	CUSTOMER COPY	SIZE:A4	SHEET:1F2 REV:A

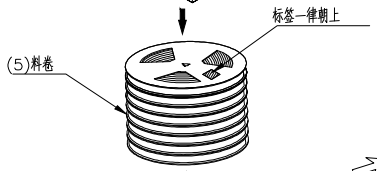
ROHS Compliant

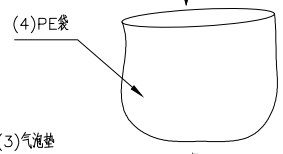
MAPX	MODIFICATION	DATE	DRAW	APPROVE

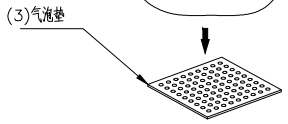


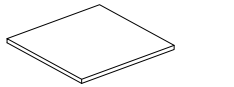


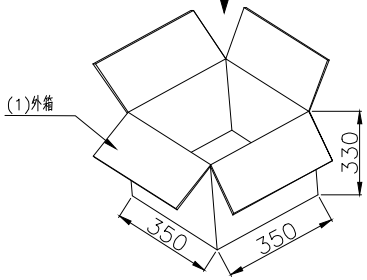


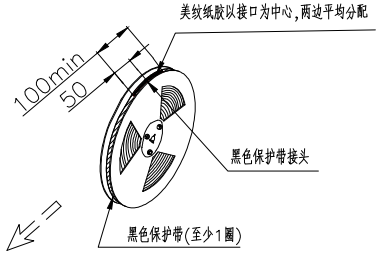


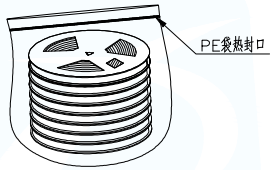


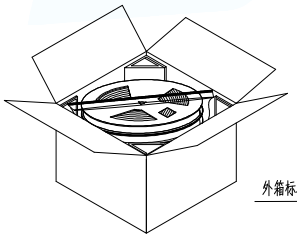


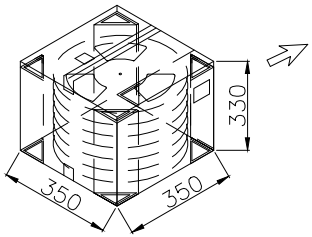


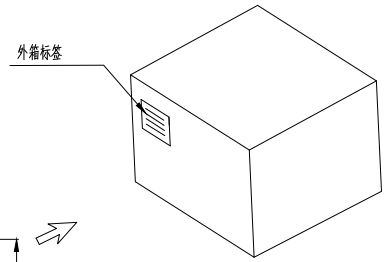


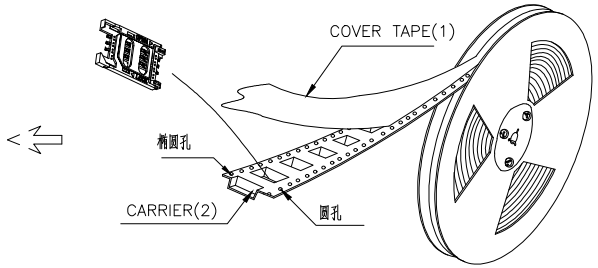


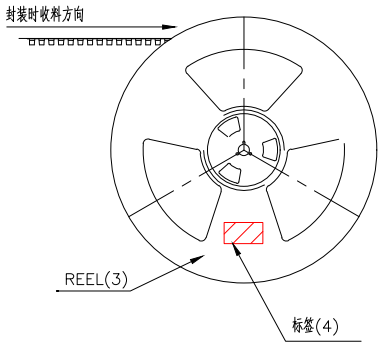




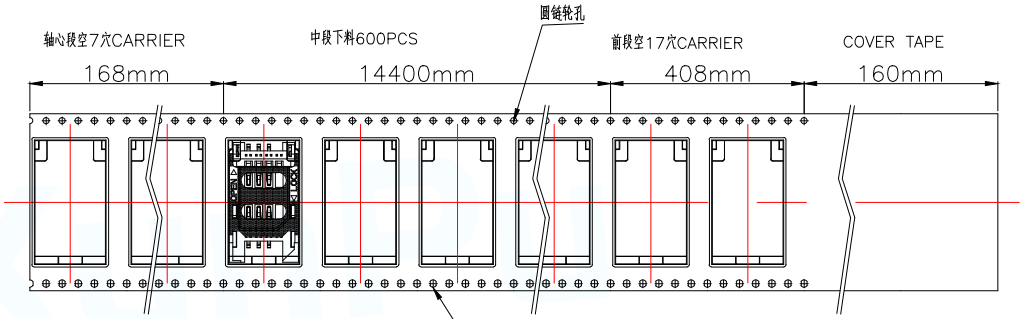








封装作业方向



一、包装流程:

1.成品置于Carrier Tape中,金属零件以不接触Carrier Tape为原则.
2.以冷封式Cover Tape与REEL紧密封好,每盘REEL共装600Pcs成品;
3.每盘包装好后需在REEL带外围用黑色保护带绕1圈包好,并以至少100mm的美纹胶封口;
4.将成品之Label贴于REEL椭圆定位孔另一边之卷盘上;
5.先置入一瓦楞纸板于纸箱底部,再置一张气泡布于瓦楞纸上,后将Reel平置于一防水袋,标签统一朝上装放(一箱共装6个Reel),封好口后置于箱中;
6.将三角板置于箱中四个角落,再置入一张气泡布于Reel之上,后置一块瓦楞纸板于最顶层;
7.以Tape封合,并贴上成品包装标签。

二、包装要求:

1.成品包装前后均需空穴,具体要求如图所示;
2.三角板置入箱中须高于REEL重叠总高度,但需低于纸箱顶面15mm以上,以确保封口后不会有外拱现象;
3.REEL盘不可有晃动现象。

三、尾数箱包装流程及要求同上.

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co,Ltd			
UNLESS OTHERWISE SPECIFED TOLERANCES			TITLE:MINI SIM CARD HINGED 全塑 6P无柱 包装图		
			PAR	SIM-107-ARP6W	
DECIMALS:	ANGLES:		DWN		
X.X:±0.15	X.°:±3°		CHKD		
X.XX:±0.10	X.X':±2'		APVD		
X.XXX:±0.08	X.XX':±1'	CUSTOMER COPY	SCALE1:1	UNIT:MM	
			SIZE:A4	SHEET:2F2	REV:A